

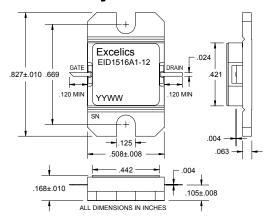
EID1516A1-12

UPDATED: 07/12/2007

15.7-16.3 GHz 12-Watt Internally Matched Power FET

FEATURES

- 15.7-16.3 GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +41.0 dBm Output Power at 1dB Compression
- 5.5 dB Power Gain at 1dB Compression
- 24% Power Added Efficiency
- Hermetic Metal Flange Package
- 100% Tested for DC, RF, and R_{TH}





Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹		MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 3200mA	f = 15.7-16.3GHz	40.0	41.0		dBm
G _{1dB}	Gain at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 3200mA	f = 15.7-16.3GHz	4.5	5.5		dB
ΔG	Gain Flatness V _{DS} = 10 V, I _{DSQ} ≈ 3200mA	f = 15.7-16.3GHz			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 3200mA			24		%
Id _{1dB}	Drain Current at 1dB Compression	f = 15.7-16.3GHz		3800	4300	mA
I _{DSS}	Saturated Drain Current	V_{DS} = 3 V, V_{GS} = 0 V		6400	8000	mA
V_{P}	Pinch-off Voltage	V_{DS} = 3 V, I_{DS} = 64 mA		-1.2	-2.5	V
R _{TH}	Thermal Resistance ²			2.5	2.9	°C/W

Notes:

- 1. Tested with 50 Ohm gate resistor.
- 2. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING^{1,2}

SYMBOL	CHARACTERISTIC	VALUE		
V _{DS}	Drain to Source Voltage	10 V		
V_{GS}	Gate to Source Voltage	-4.5 V		
I _{DS}	Drain Current	IDSS		
I_{GSF}	Forward Gate Current	220 mA		
P _{IN}	Input Power	@ 3dB compression		
P_{T}	Total Power Dissipation	52 W		
T _{CH}	Channel Temperature	175°C		
T _{STG}	Storage Temperature	-65/+175°C		

Note: 1. Exceeding any of the above ratings may result in permanent damage.

^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.



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